Final Product Change Notification

202502007F01 : PCA9450 / MP90 Dual Wafer Fabrication Source Expansion from SSMC to PSMC

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 25, 2025 **Effective Date:** Jul 25, 2025

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For detailed information we invite you to view this notification online

Management summary

NXP Semiconductors announces the addition of wafer fab Powerchip Semiconductor Manufacturing Corporation (PSMC, Hsinchu Taiwan) for PCA9450 / MP90 products. Currently product is sourced from wafer fab Systems on Silicon Manufacturing Company (SSMC, Singapore). The addition of Powerchip wafer fab creates more sourcing reliability, flexibility, and capacity expansion.

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[ ]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[ ]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[X]Wafer Fab Location	[ ]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[ ]Other			

Notification Overview

Description

NXP Semiconductors announces the addition of wafer fab Powerchip Semiconductor Manufacturing Corporation (PSMC, Hsinchu Taiwan) for PCA9450 / MP90 products. Currently product is sourced from wafer fab Systems on Silicon Manufacturing Company (SSMC, Singapore). The addition of Powerchip wafer fab creates more sourcing reliability, flexibility, and capacity expansion.

The dual wafer fab sourcing of the PCA9450x / MP90 products from SSMC and Powerchip results in:
- No change to orderable part number / 12NC
- No change to data sheet
- No change to Bill of Material (BOM) items
- No change to Assembly and Package site locations

PSMC wafer fab qualification has successfully completed - please see attachment for additional details / qualification results.

Reason

The addition of Powerchip wafer fab creates more sourcing reliability, flexibility, and capacity expansion.

Identification of Affected Products

Topside marking will reflect the Powerchip wafer fab marking; the wafer fab in marking line D will change to "S" for Powerchip.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jul 25, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Dual fab sourcing - no impact.

Additional information

Self qualification:view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 25, 2025.

In compliance with JEDEC J-STD-048, potential Last Time Buy orders shall be placed before Last Time Buy Date.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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